# Felt-based Polishing Pad

# **SUBATM**

SUBA<sup>™</sup> pad is foamed by non-woven felt which polyurethane is coagulated. SUBA<sup>™</sup> shows excellent performance at stock polishing in silicon wafer, sapphire wafer and oxide material wafer.

#### **SUBA™** Series

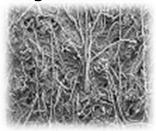
SUBA™ pad is designed for stock removal and semi-final process of silicon wafer polishing. Also, it's available for the edge and notch polishing of silicon wafer. There are many product lines to cover each process requirement.



#### Advantages

- 1. High removal rate
- 2. Low defectivity
- 3. Excellent flatness

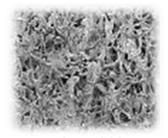
### ■ SEM Image







SUBA600



SUBA800

## ■ Physical Properties

Product	Thickness (mm)	Hardness (Asker C)	Compressibility (%)
SUBA™ 400	1.27	60	9.4
SUBA™ 600	1.27	80	4.2
SUBA™ 800	1.27	83	3.3
SUBA™ 840	1.27	84	2.6
SUBA™ 800M2	1.27	87	2.7

<sup>\*\*</sup> The values such as a physical property indicated, show the standard value. The product specifications are not guaranteed.